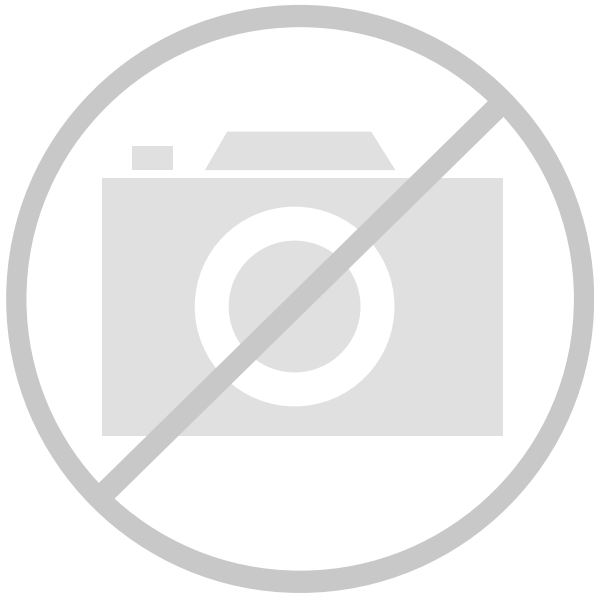




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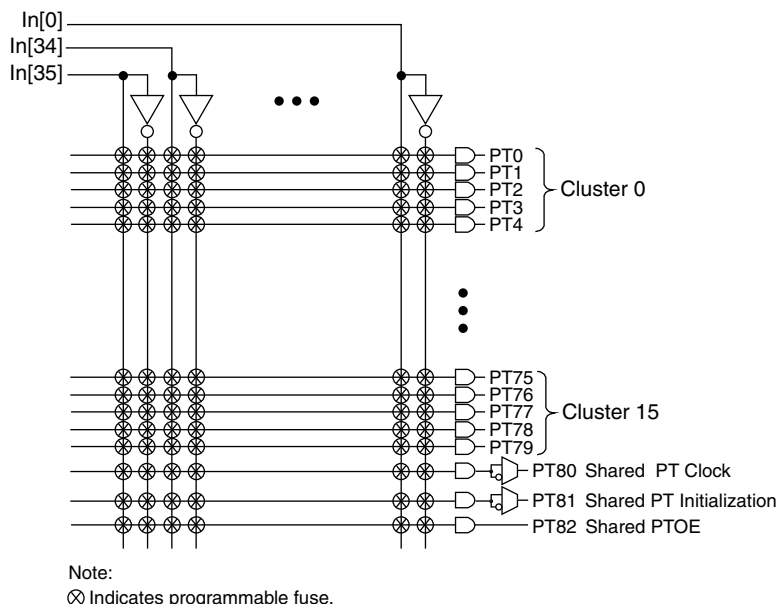
Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	2.3V ~ 2.7V
Number of Logic Elements/Blocks	32
Number of Macrocells	512
Number of Gates	-
Number of I/O	208
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	256-LBGA
Supplier Device Package	256-FTBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4512b-5ft256c

Figure 3. AND Array

Enhanced Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in product term clusters. Each product term cluster is associated with a macrocell. The cluster size for the ispMACH 4000 family is 4+1 (total 5) product terms. The software automatically considers the availability and distribution of product term clusters as it fits the functions within a GLB. The logic allocator is designed to provide three speed paths: 5-PT fast bypass path, 20-PT Speed Locking path and an up to 80-PT path. The availability of these three paths lets designers trade timing variability for increased performance.

The enhanced Logic Allocator of the ispMACH 4000 family consists of the following blocks:

- Product Term Allocator
- Cluster Allocator
- Wide Steering Logic

Figure 4 shows a macrocell slice of the Logic Allocator. There are 16 such slices in the GLB.

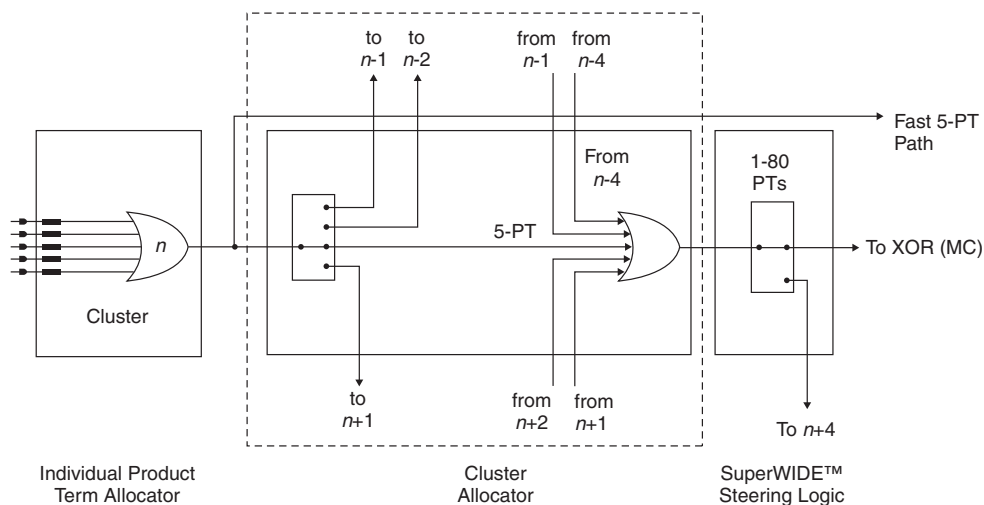
Figure 4. Macrocell Slice

Table 5. Product Term Expansion Capability

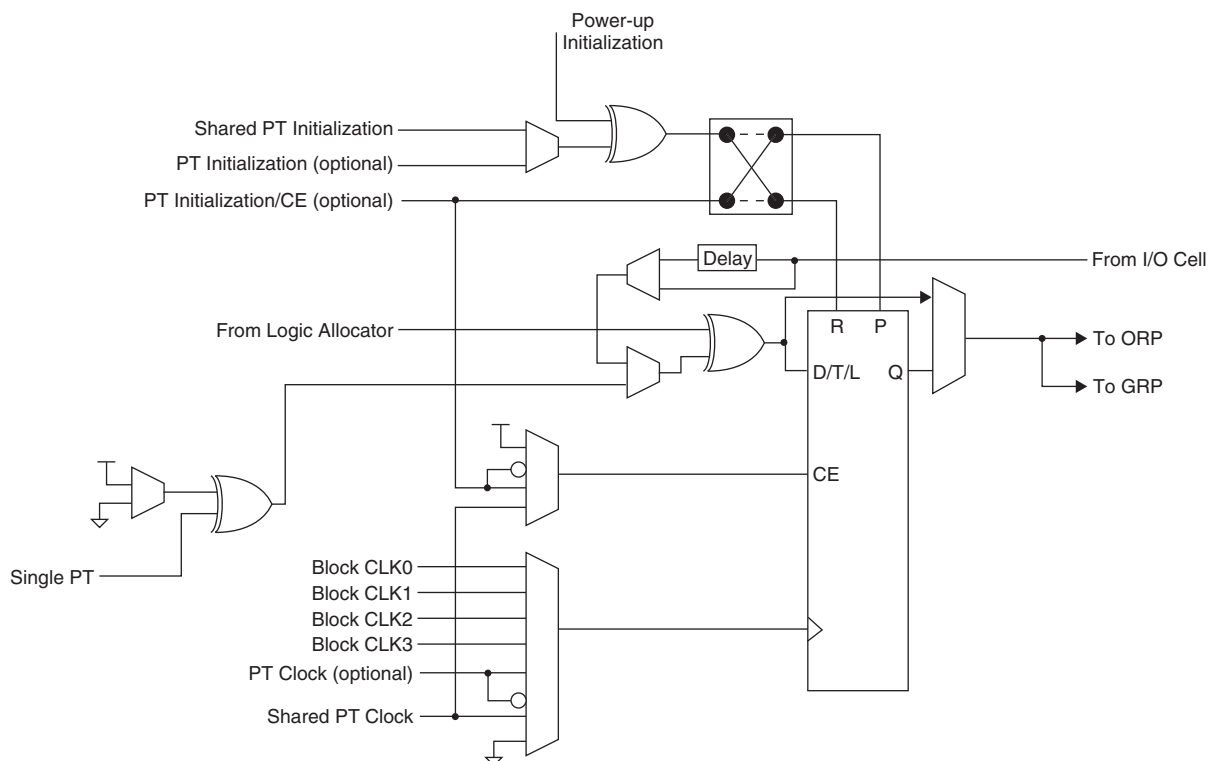
Expansion Chains	Macrocells Associated with Expansion Chain (with Wrap Around)	Max PT/Macrocell
Chain-0	M0 M4 M8 M12 M0	75
Chain-1	M1 M5 M9 M13 M1	80
Chain-2	M2 M6 M10 M14 M2	75
Chain-3	M3 M7 M11 M15 M3	70

Every time the super cluster allocator is used, there is an incremental delay of t_{EXP} . When the super cluster allocator is used, all destinations other than the one being steered to, are given the value of ground (i.e., if the super cluster is steered to $M(n+4)$, then $M(n)$ is ground).

Macrocell

The 16 macrocells in the GLB are driven by the 16 outputs from the logic allocator. Each macrocell contains a programmable XOR gate, a programmable register/latch, along with routing for the logic and control functions. Figure 5 shows a graphical representation of the macrocell. The macrocells feed the ORP and GRP. A direct input from the I/O cell allows designers to use the macrocell to construct high-speed input registers. A programmable delay in this path allows designers to choose between the fastest possible set-up time and zero hold time.

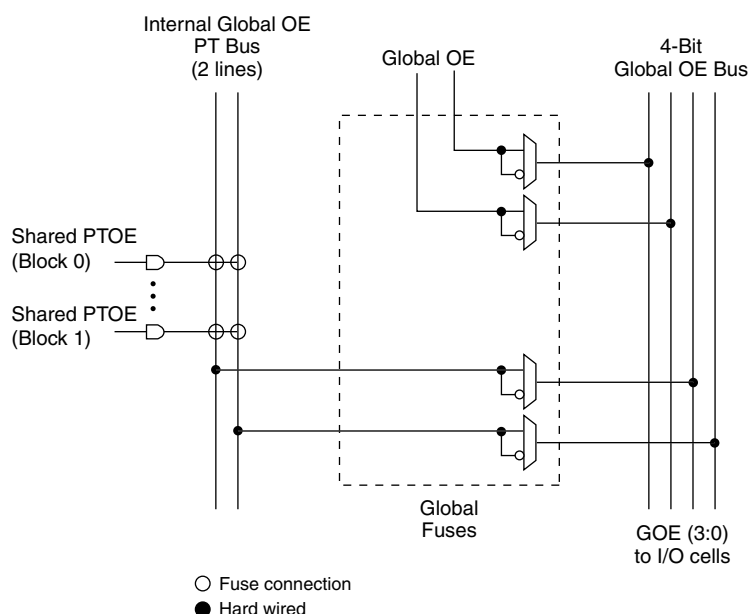
Figure 5. Macrocell



Enhanced Clock Multiplexer

The clock input to the flip-flop can select any of the four block clocks along with the shared PT clock, and true and complement forms of the optional individual term clock. An 8:1 multiplexer structure is used to select the clock. The eight sources for the clock multiplexer are as follows:

- Block CLK0
- Block CLK1

Figure 10. Global OE Generation for ispMACH 4032

Zero Power/Low Power and Power Management

The ispMACH 4000 family is designed with high speed low power design techniques to offer both high speed and low power. With an advanced E² low power cell and non sense-amplifier design approach (full CMOS logic approach), the ispMACH 4000 family offers SuperFAST pin-to-pin speeds, while simultaneously delivering low standby power without needing any “turbo bits” or other power management schemes associated with a traditional sense-amplifier approach.

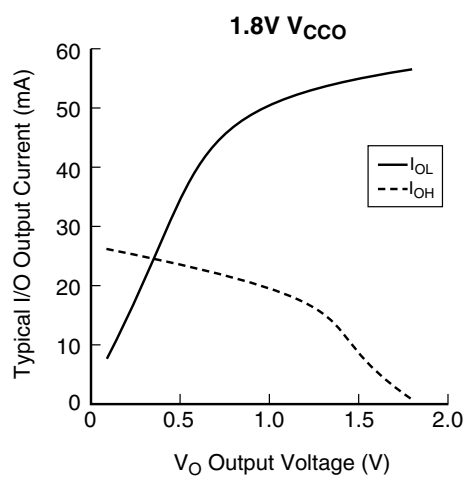
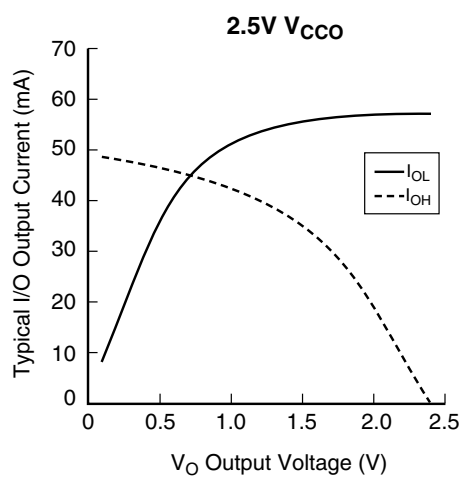
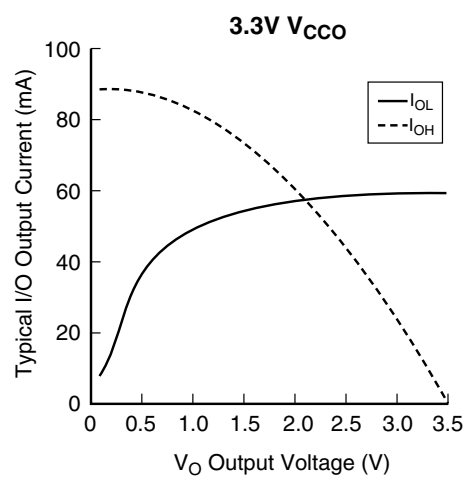
The zero power ispMACH 4000Z is based on the 1.8V ispMACH 4000C family. With innovative circuit design changes, the ispMACH 4000Z family is able to achieve the industry’s “lowest static power”.

IEEE 1149.1-Compliant Boundary Scan Testability

All ispMACH 4000 devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more board-level testing. The test access port operates with an LVCMOS interface that corresponds to the power supply voltage.

I/O Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os’ physical nature should be minimal so that board test time is minimized. The ispMACH 4000 family of devices allows this by offering the user the ability to quickly configure the physical nature of the I/O cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice’s ispVM[®] System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.



ispMACH 4000V/B/C External Switching Characteristics (Cont.)**Over Recommended Operating Conditions**

Parameter	Description ^{1, 2, 3}	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{PD}	5-PT bypass combinatorial propagation delay	—	5.0	—	7.5	—	10.0	ns
t_{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	5.5	—	8.0	—	10.5	ns
t_S	GLB register setup time before clock	3.0	—	4.5	—	5.5	—	ns
t_{ST}	GLB register setup time before clock with T-type register	3.2	—	4.7	—	5.5	—	ns
t_{SIR}	GLB register setup time before clock, input register path	1.2	—	1.7	—	1.7	—	ns
t_{SIRZ}	GLB register setup time before clock with zero hold	2.2	—	2.7	—	2.7	—	ns
t_H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t_{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t_{HIR}	GLB register hold time after clock, input register path	1.0	—	1.0	—	1.0	—	ns
t_{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t_{CO}	GLB register clock-to-output delay	—	3.4	—	4.5	—	6.0	ns
t_R	External reset pin to output delay	—	6.3	—	9.0	—	10.5	ns
t_{RW}	External reset pulse duration	2.0	—	4.0	—	4.0	—	ns
$t_{PTOE/DIS}$	Input to output local product term output enable/disable	—	7.0	—	9.0	—	10.5	ns
$t_{GPTOE/DIS}$	Input to output global product term output enable/disable	—	9.0	—	10.3	—	12.0	ns
$t_{GOE/DIS}$	Global OE input to output enable/disable	—	5.0	—	7.0	—	8.0	ns
t_{CW}	Global clock width, high or low	2.2	—	2.8	—	4.0	—	ns
t_{GW}	Global gate width low (for low transparent) or high (for high transparent)	2.2	—	2.8	—	4.0	—	ns
t_{WIR}	Input register clock width, high or low	2.2	—	2.8	—	4.0	—	ns
f_{MAX}^4	Clock frequency with internal feedback	—	227	—	168	—	125	MHz
f_{MAX} (Ext.)	Clock frequency with external feedback, $[1/(t_S + t_{CO})]$	—	156	—	111	—	86	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.3.2

2. Measured using standard switching circuit, assuming GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

ispMACH 4000Z External Switching Characteristics (Cont.)

Over Recommended Operating Conditions

Parameter	Description ^{1, 2, 3}	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	5-PT bypass combinatorial propagation delay	—	4.5	—	5.0	—	7.5	ns
t _{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	5.8	—	6.0	—	8.0	ns
t _S	GLB register setup time before clock	2.9	—	3.0	—	4.5	—	ns
t _{ST}	GLB register setup time before clock with T-type register	3.1	—	3.2	—	4.7	—	ns
t _{SIR}	GLB register setup time before clock, input register path	1.3	—	1.3	—	1.4	—	ns
t _{SIRZ}	GLB register setup time before clock with zero hold	2.6	—	2.6	—	2.7	—	ns
t _H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t _{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time after clock, input register path	1.3	—	1.3	—	1.3	—	ns
t _{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	3.8	—	4.2	—	4.5	ns
t _R	External reset pin to output delay	—	7.5	—	7.5	—	9.0	ns
t _{RW}	External reset pulse duration	2.0	—	2.0	—	4.0	—	ns
t _{PTOE/DIS}	Input to output local product term output enable/disable	—	8.2	—	8.5	—	9.0	ns
t _{GPTOE/DIS}	Input to output global product term output enable/disable	—	10.0	—	10.0	—	10.5	ns
t _{GOE/DIS}	Global OE input to output enable/disable	—	5.5	—	6.0	—	7.0	ns
t _{CW}	Global clock width, high or low	1.8	—	2.0	—	2.8	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.8	—	2.0	—	2.8	—	ns
t _{WIR}	Input register clock width, high or low	1.8	—	2.0	—	2.8	—	ns
f _{MAX} ⁴	Clock frequency with internal feedback	—	200	—	200	—	168	MHz
f _{MAX} (Ext.)	clock frequency with external feedback, [1 / (t _S + t _{CO})]	—	150	—	139	—	111	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.2.2

2. Measured using standard switching GRP loading of 1 and 1 output switching.

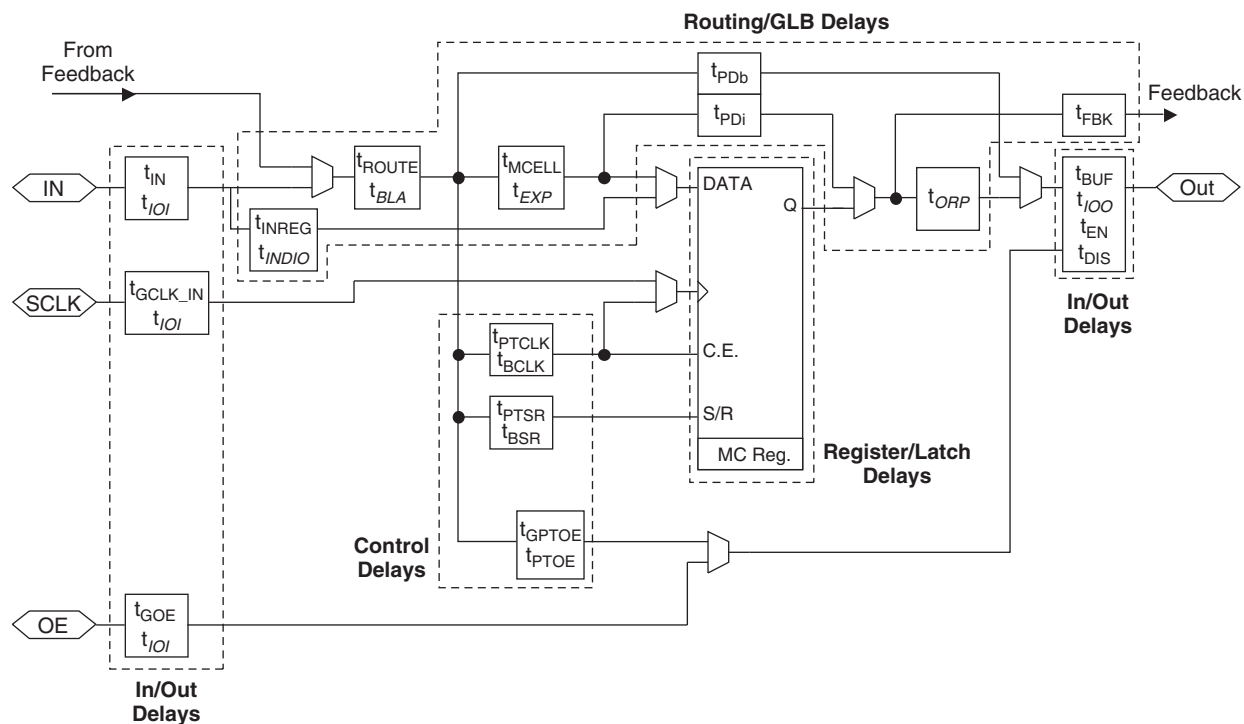
3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

Timing Model

The task of determining the timing through the ispMACH 4000 family, like any CPLD, is relatively simple. The timing model provided in Figure 11 shows the specific delay paths. Once the implementation of a given function is determined either conceptually or from the software report file, the delay path of the function can easily be determined from the timing model. The Lattice design tools report the timing delays based on the same timing model for a particular design. Note that the internal timing parameters are given for reference only, and are not tested. The external timing parameters are tested and guaranteed for every device. For more information on the timing model and usage, refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#).

Figure 11. ispMACH 4000 Timing Model



Note: Italicized items are optional delay adders.

ispMACH 4000Z Internal Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays								
t _{IN}	Input Buffer Delay	—	0.75	—	0.80	—	0.75	ns
t _{GOE}	Global OE Pin Delay	—	2.25	—	2.25	—	2.30	ns
t _{GCLK_IN}	Global Clock Input Buffer Delay	—	1.60	—	1.60	—	1.95	ns
t _{BUF}	Delay through Output Buffer	—	0.75	—	0.90	—	0.90	ns
t _{EN}	Output Enable Time	—	2.25	—	2.25	—	2.50	ns
t _{DIS}	Output Disable Time	—	1.35	—	1.35	—	2.50	ns
Routing/GLB Delays								
t _{ROUTE}	Delay through GRP	—	1.60	—	1.60	—	2.15	ns
t _{MCELL}	Macrocell Delay	—	0.65	—	0.75	—	0.85	ns
t _{INREG}	Input Buffer to Macrocell Register Delay	—	0.91	—	1.00	—	1.00	ns
t _{FBK}	Internal Feedback Delay	—	0.05	—	0.00	—	0.00	ns
t _{PDb}	5-PT Bypass Propagation Delay	—	0.40	—	0.40	—	0.40	ns
t _{PDi}	Macrocell Propagation Delay	—	0.25	—	0.25	—	0.65	ns
Register/Latch Delays								
t _S	D-Register Setup Time (Global Clock)	0.80	—	0.95	—	0.90	—	ns
t _{S_PT}	D-Register Setup Time (Product Term Clock)	1.35	—	1.95	—	1.90	—	ns
t _{ST}	T-Register Setup Time (Global Clock)	1.00	—	1.15	—	1.10	—	ns
t _{ST_PT}	T-register Setup Time (Product Term Clock)	1.55	—	1.75	—	2.10	—	ns
t _H	D-Register Hold Time	1.40	—	1.55	—	1.80	—	ns
t _{HT}	T-Resister Hold Time	1.40	—	1.55	—	1.80	—	ns
t _{SIR}	D-Input Register Setup Time (Global Clock)	0.94	—	0.90	—	1.50	—	ns
t _{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
t _{HIR}	D-Input Register Hold Time (Global Clock)	1.06	—	1.20	—	1.10	—	ns
t _{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	0.88	—	1.00	—	1.00	—	ns
t _{COi}	Register Clock to Output/Feedback MUX Time	—	0.65	—	0.70	—	0.65	ns
t _{CES}	Clock Enable Setup Time	1.00	—	2.00	—	2.00	—	ns
t _{CEH}	Clock Enable Hold Time	0.00	—	0.00	—	0.00	—	ns
t _{SL}	Latch Setup Time (Global Clock)	0.80	—	0.95	—	0.90	—	ns
t _{SL_PT}	Latch Setup Time (Product Term Clock)	1.55	—	1.95	—	1.90	—	ns
t _{HL}	Latch Hold Time	1.40	—	1.80	—	1.80	—	ns
t _{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.40	—	0.33	—	0.33	ns
t _{PDLi}	Propagation Delay through Transparent Latch to Output/ Feedback MUX	—	0.30	—	0.25	—	0.25	ns
t _{SRI}	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.28	—	0.28	—	1.27	ns
t _{SRR}	Asynchronous Reset or Set Recovery Delay	—	2.00	—	1.67	—	1.80	ns
Control Delays								
t _{BCLK}	GLB PT Clock Delay	—	1.30	—	1.50	—	1.55	ns
t _{PTCLK}	Macrocell PT Clock Delay	—	1.50	—	1.70	—	1.55	ns
t _{BSR}	GLB PT Set/Reset Delay	—	1.10	—	1.83	—	1.83	ns
t _{PTSR}	Macrocell PT Set/Reset Delay	—	1.22	—	2.02	—	1.83	ns

ispMACH 4000Z Internal Timing Parameters (Cont.)**Over Recommended Operating Conditions**

Parameter	Description	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{P_{TOE}}	Macrocell PT OE Delay	—	2.50	—	2.70	—	2.00	ns

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the timing model in this data sheet for further details.

Timing v.2.2

Boundary Scan Waveforms and Timing Specifications

Symbol	Parameter	Min.	Max.	Units
t_{BTCP}	TCK [BSCAN test] clock cycle	40	—	ns
t_{BTCH}	TCK [BSCAN test] pulse width high	20	—	ns
t_{BTCL}	TCK [BSCAN test] pulse width low	20	—	ns
t_{BTSU}	TCK [BSCAN test] setup time	8	—	ns
t_{BTH}	TCK [BSCAN test] hold time	10	—	ns
t_{BRF}	TCK [BSCAN test] rise and fall time	50	—	mV/ns
t_{BTCO}	TAP controller falling edge of clock to valid output	—	10	ns
t_{BTOZ}	TAP controller falling edge of clock to data output disable	—	10	ns
t_{BTVO}	TAP controller falling edge of clock to data output enable	—	10	ns
t_{BTCPSU}	BSCAN test Capture register setup time	8	—	ns
t_{BTCPH}	BSCAN test Capture register hold time	10	—	ns
t_{BTUCO}	BSCAN test Update reg, falling edge of clock to valid output	—	25	ns
t_{BTUOZ}	BSCAN test Update reg, falling edge of clock to output disable	—	25	ns
t_{BTUOV}	BSCAN test Update reg, falling edge of clock to output enable	—	25	ns

Signal Descriptions

Signal Names	Description
TMS	Input – This pin is the IEEE 1149.1 Test Mode Select input, which is used to control the state machine.
TCK	Input – This pin is the IEEE 1149.1 Test Clock input pin, used to clock through the state machine.
TDI	Input – This pin is the IEEE 1149.1 Test Data In pin, used to load data.
TDO	Output – This pin is the IEEE 1149.1 Test Data Out pin used to shift data out.
GOE0/IO, GOE1/IO	These pins are configured to be either Global Output Enable Input or as general I/O pins.
GND	Ground
NC	Not Connected
V _{CC}	The power supply pins for logic core and JTAG port.
CLK0/I, CLK1/I, CLK2/I, CLK3/I	These pins are configured to be either CLK input or as an input.
V _{CC00} , V _{CC01}	The power supply pins for each I/O bank.
yzz	Input/Output ¹ – These are the general purpose I/O used by the logic array. y is GLB reference (alpha) and z is macrocell reference (numeric). z: 0-15.
	ispMACH 4032 y: A-B
	ispMACH 4064 y: A-D
	ispMACH 4128 y: A-H
	ispMACH 4256 y: A-P
	ispMACH 4384 y: A-P, AX-HX
	ispMACH 4512 y: A-P, AX-PX

1. In some packages, certain I/Os are only available for use as inputs. See the signal connections table for details.

ispMACH 4000V/B/C ORP Reference Table

	4032V/B/C		4064V/B/C			4128V/B/C			4256V/B/C				4384V/B/C		4512V/B/C	
Number of I/Os	30 ¹	32	30 ²	32	64	64	92 ³	96	64	96 ⁴	128	160	128	192	128	208
Number of GLBs	2	2	4	4	4	8	8	8	16	16	16	16	16	16	16	16
Number of I/Os / GLB	16	16	8	8	16	8	12	12	4	8	8	10	8	8	8	Mixture of 8 & 4 ⁵
Reference ORP Table	16 I/Os / GLB		8 I/Os / GLB		16 I/Os / GLB	8 I/Os / GLB	12 I/Os / GLB	4 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB	10 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB 4 I/Os / GLB	

1. 32-macrocell device, 44 TQFP: 2 GLBs have 15 out of 16 I/Os bonded out.

2. 64-macrocells device, 44 TQFP: 2 GLBs have 7 out of 8 I/Os bonded out.

3. 128-macrocell device, 128 TQFP: 4 GLBs have 11 out of 12 I/Os

4. 256-macrocell device, 144 TQFP: 16 GLBs have 6 I/Os per

5. 512-macrocell device: 20 GLBs have 8 I/Os per, 12 GLBs have 4 I/Os per

ispMACH 4000Z ORP Reference Table

	4032Z	4064Z		4128Z		4256Z		
Number of I/Os	32	32	64	64	96	64	96 ¹	128
Number of GLBs	2	4	4	8	8	16	16	16
Number of I/Os / GLB	16	8	16	8	12	4	8	8
Reference ORP Table	16 I/Os / GLB	8 I/Os / GLB	16 I/Os / GLB	8 I/Os / GLB	12 I/Os / GLB	4 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB

1. 256-macrocell device, 132 csBGA: 16 GLBs have 6 I/Os per

**ispMACH 4032V/B/C/Z and 4064V/B/C/Z Logic Signal Connections:
48-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4032V/B/C/Z		ispMACH 4064V/B/C		ispMACH 4064Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
33	1	B10	B [^] 10	D4	D [^] 2	D10	D [^] 5
34	1	B11	B [^] 11	D6	D [^] 3	D8	D [^] 4
35	-	TDO	-	TDO	-	TDO	-
36	-	VCC	-	VCC	-	VCC	-
37	-	GND	-	GND	-	GND	-
38	1	B12	B [^] 12	D8	D [^] 4	D6	D [^] 3
39	1	B13	B [^] 13	D10	D [^] 5	D4	D [^] 2
40	1	B14	B [^] 14	D12	D [^] 6	D2	D [^] 1
41	1	B15/GOE1	B [^] 15	D14/GOE1	D [^] 7	D0/GOE1	D [^] 0
42	1	CLK3/I	-	CLK3/I	-	CLK3/I	-
43	0	CLK0/I	-	CLK0/I	-	CLK0/I	-
44	0	A0/GOE0	A [^] 0	A0/GOE0	A [^] 0	A0/GOE0	A [^] 0
45	0	A1	A [^] 1	A2	A [^] 1	A1	A [^] 1
46	0	A2	A [^] 2	A4	A [^] 2	A2	A [^] 2
47	0	A3	A [^] 3	A6	A [^] 3	A4	A [^] 3
48	0	A4	A [^] 4	A8	A [^] 4	A6	A [^] 4

ispMACH 4032Z and 4064Z Logic Signal Connections: 56-Ball csBGA

Ball Number	Bank Number	ispMACH 4032Z		ispMACH 4064Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
B1	-	TDI	-	TDI	-
C3	0	A5	A [^] 5	A8	A [^] 5
C1	0	A6	A [^] 6	A10	A [^] 6
D1	0	A7	A [^] 7	A11	A [^] 7
D3	0	GND (Bank 0)	-	GND (Bank 0)	-
E3	0	NC ¹	-	I ¹	-
E1	0	NC ¹	-	I ¹	-
F3	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
F1	0	A8	A [^] 8	B15	B [^] 7
G3	0	A9	A [^] 9	B12	B [^] 6
G1	0	A10	A [^] 10	B10	B [^] 5
H1	0	A11	A [^] 11	B8	B [^] 4
J1	0	NC	-	I	-
K1	-	TCK	-	TCK	-
K2	-	VCC	-	VCC	-
H3	-	GND	-	GND	-
K3	-	NC ¹	-	I ¹	-
K4	0	A12	A [^] 12	B6	B [^] 3
H4	0	A13	A [^] 13	B4	B [^] 2
H5	0	A14	A [^] 14	B2	B [^] 1

**ispMACH 4064V/B/C/Z, 4128V/B/C/Z, 4256V/B/C/Z Logic Signal Connections:
100-Pin TQFP**

Pin Number	Bank Number	ispMACH 4064V/B/C/Z		ispMACH 4128V/B/C/Z		ispMACH 4256V/B/C/Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	GND	-	GND	-	GND	-
2	-	TDI	-	TDI	-	TDI	-
3	0	A8	A^8	B0	B^0	C12	C^3
4	0	A9	A^9	B2	B^1	C10	C^2
5	0	A10	A^10	B4	B^2	C6	C^1
6	0	A11	A^11	B6	B^3	C2	C^0
7	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
8	0	A12	A^12	B8	B^4	D12	D^3
9	0	A13	A^13	B10	B^5	D10	D^2
10	0	A14	A^14	B12	B^6	D6	D^1
11	0	A15	A^15	B13	B^7	D4	D^0
12*	0	I	-	I	-	I	-
13	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
14	0	B15	B^15	C14	C^7	E4	E^0
15	0	B14	B^14	C12	C^6	E6	E^1
16	0	B13	B^13	C10	C^5	E10	E^2
17	0	B12	B^12	C8	C^4	E12	E^3
18	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
19	0	B11	B^11	C6	C^3	F2	F^0
20	0	B10	B^10	C5	C^2	F6	F^1
21	0	B9	B^9	C4	C^1	F10	F^2
22	0	B8	B^8	C2	C^0	F12	F^3
23*	0	I	-	I	-	I	-
24	-	TCK	-	TCK	-	TCK	-
25	-	VCC	-	VCC	-	VCC	-
26	-	GND	-	GND	-	GND	-
27*	0	I	-	I	-	I	-
28	0	B7	B^7	D13	D^7	G12	G^3
29	0	B6	B^6	D12	D^6	G10	G^2
30	0	B5	B^5	D10	D^5	G6	G^1
31	0	B4	B^4	D8	D^4	G2	G^0
32	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
33	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
34	0	B3	B^3	D6	D^3	H12	H^3
35	0	B2	B^2	D4	D^2	H10	H^2
36	0	B1	B^1	D2	D^1	H6	H^1
37	0	B0	B^0	D0	D^0	H2	H^0
38	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
39	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
40	-	VCC	-	VCC	-	VCC	-
41	1	C0	C^0	E0	E^0	I2	I^0

**ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections:
132-Ball csBGA (Cont.)**

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
E3	0	NC	-	B8	B ⁶	D12	D ⁶
F2	0	A12	A ¹²	B9	B ⁷	D10	D ⁵
F1	0	A13	A ¹³	B10	B ⁸	D8	D ⁴
F3	0	A14	A ¹⁴	B12	B ⁹	D6	D ³
G1	0	A15	A ¹⁵	B13	B ¹⁰	D4	D ²
G2	0	I	-	B14	B ¹¹	D2	D ¹
G3	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
H2	0	NC	-	C14	C ¹¹	E2	E ¹
H1	0	B15	B ¹⁵	C13	C ¹⁰	E4	E ²
H3	0	B14	B ¹⁴	C12	C ⁹	E6	E ³
J1	0	B13	B ¹³	C10	C ⁸	E8	E ⁴
J2	0	B12	B ¹²	C9	C ⁷	E10	E ⁵
J3	0	NC	-	C8	C ⁶	E12	E ⁶
K2	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
K1	0	NC	-	C6	C ⁵	F2	F ¹
K3	0	B11	B ¹¹	C5	C ⁴	F4	F ²
L2	0	B10	B ¹⁰	C4	C ³	F6	F ³
L1	0	B9	B ⁹	C2	C ²	F8	F ⁴
L3	0	B8	B ⁸	C1	C ¹	F10	F ⁵
M1	0	I	-	C0	C ⁰	F12	F ⁶
M2	0	NC	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
N1	-	TCK	-	TCK	-	TCK	-
P1	-	VCC	-	VCC	-	VCC	-
P2	-	GND	-	GND	-	GND	-
N2	0	I	-	D14	D ¹¹	G12	G ⁶
P3	0	B7	B ⁷	D13	D ¹⁰	G10	G ⁵
M3	0	B6	B ⁶	D12	D ⁹	G8	G ⁴
N3	0	B5	B ⁵	D10	D ⁸	G6	G ³
P4	0	B4	B ⁴	D9	D ⁷	G4	G ²
M4	0	NC	-	D8	D ⁶	G2	G ¹
N4	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
P5	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
N5	0	NC	-	D6	D ⁵	H12	H ⁶
M5	0	B3	B ³	D5	D ⁴	H10	H ⁵
N6	0	B2	B ²	D4	D ³	H8	H ⁴
P6	0	B1	B ¹	D2	D ²	H6	H ³
M6	0	B0	B ⁰	D1	D ¹	H4	H ²
P7	0	NC	-	D0	D ⁰	H2	H ¹
N7	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
M7	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
N8	-	VCC	-	VCC	-	VCC	-

**ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections:
176-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
101	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
102	1	L14	L ¹⁴	AX14	AX ¹⁴	GX14	GX ¹⁴
103	1	L12	L ¹²	AX12	AX ¹²	GX12	GX ¹²
104	1	L10	L ¹⁰	AX10	AX ¹⁰	GX10	GX ¹⁰
105	1	L8	L ⁸	AX8	AX ⁸	GX8	GX ⁸
106	1	L6	L ⁶	AX6	AX ⁶	GX6	GX ⁶
107	1	L4	L ⁴	AX4	AX ⁴	GX4	GX ⁴
108	1	L2	L ²	AX2	AX ²	GX2	GX ²
109	1	L0	L ⁰	AX0	AX ⁰	GX0	GX ⁰
110	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
111	1	M0	M ⁰	DX0	DX ⁰	JX0	JX ⁰
112	1	M2	M ²	DX2	DX ²	JX2	JX ²
113	1	M4	M ⁴	DX4	DX ⁴	JX4	JX ⁴
114	1	M6	M ⁶	DX6	DX ⁶	JX6	JX ⁶
115	1	M8	M ⁸	DX8	DX ⁸	JX8	JX ⁸
116	1	M10	M ¹⁰	DX10	DX ¹⁰	JX10	JX ¹⁰
117	1	M12	M ¹²	DX12	DX ¹²	JX12	JX ¹²
118	1	M14	M ¹⁴	DX14	DX ¹⁴	JX14	JX ¹⁴
119	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
120	1	N0	N ⁰	FX0	FX ⁰	NX0	NX ⁰
121	1	N2	N ²	FX2	FX ²	NX2	NX ²
122	1	N4	N ⁴	FX4	FX ⁴	NX4	NX ⁴
123	1	N6	N ⁶	FX6	FX ⁶	NX6	NX ⁶
124	1	N8	N ⁸	FX8	FX ⁸	NX8	NX ⁸
125	1	N10	N ¹⁰	FX10	FX ¹⁰	NX10	NX ¹⁰
126	1	N12	N ¹²	FX12	FX ¹²	NX12	NX ¹²
127	1	N14	N ¹⁴	FX14	FX ¹⁴	NX14	NX ¹⁴
128	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
129	-	TDO	-	TDO	-	TDO	-
130	-	VCC	-	VCC	-	VCC	-
131	-	NC	-	NC	-	NC	-
132	-	NC	-	NC	-	NC	-
133	-	NC	-	NC	-	NC	-
134	-	GND	-	GND	-	GND	-
135	1	O14	O ¹⁴	GX14	GX ¹⁴	OX14	OX ¹⁴
136	1	O12	O ¹²	GX12	GX ¹²	OX12	OX ¹²
137	1	O10	O ¹⁰	GX10	GX ¹⁰	OX10	OX ¹⁰
138	1	O8	O ⁸	GX8	GX ⁸	OX8	OX ⁸
139	1	O6	O ⁶	GX6	GX ⁶	OX6	OX ⁶
140	1	O4	O ⁴	GX4	GX ⁴	OX4	OX ⁴
141	1	O2	O ²	GX2	GX ²	OX2	OX ²

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
-	-	-	-	-	-	VCC	-	VCC	-
-	-	GND	-	GND	-	GND	-	GND	-
C3	-	TDI	-	TDI	-	TDI	-	TDI	-
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
B1	0	C14	C ⁷	C14	C ⁹	C14	C ⁷	C14	C ⁷
F5	0	C12	C ⁶	C12	C ⁸	C12	C ⁶	C12	C ⁶
D3	0	C10	C ⁵	C10	C ⁷	C10	C ⁵	C10	C ⁵
C1	0	C8	C ⁴	C9	C ⁶	C8	C ⁴	C8	C ⁴
C2	0	C6	C ³	C8	C ⁵	C6	C ³	C6	C ³
E3	0	C4	C ²	C6	C ⁴	C4	C ²	C4	C ²
D2	0	C2	C ¹	C4	C ³	C2	C ¹	C2	C ¹
F6	0	C0	C ⁰	C2	C ²	C0	C ⁰	C0	C ⁰
D1	0	NC	-	C1	C ¹	F6	F ³	H0	H ⁰
E2	0	NC	-	C0	C ⁰	F4	F ²	H4	H ¹
E4	0	NC	-	NC	-	D6	D ³	F4	F ²
G5	0	NC	-	NC	-	D4	D ²	F6	F ³
E1	0	NC	-	NC	-	NC	-	F8	F ⁴
-	0	-	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
F2	0	NC	-	NC	-	NC	-	F10	F ⁵
F1	0	NC	-	NC	-	D2	D ¹	F12	F ⁶
G1	0	NC	-	NC	-	D0	D ⁰	F14	F ⁷
G6	0	NC	-	D14	D ⁹	F2	F ¹	H8	H ²
G4	0	NC	-	D12	D ⁸	F0	F ⁰	H12	H ³
H6	0	D14	D ⁷	D10	D ⁷	E14	E ⁷	G14	G ⁷
G3	0	D12	D ⁶	D9	D ⁶	E12	E ⁶	G12	G ⁶
H5	0	D10	D ⁵	D8	D ⁵	E10	E ⁵	G10	G ⁵
G2	0	D8	D ⁴	D6	D ⁴	E8	E ⁴	G8	G ⁴
H1	0	D6	D ³	D4	D ³	E6	E ³	G6	G ³
H2	0	D4	D ²	D2	D ²	E4	E ²	G4	G ²
H3	0	D2	D ¹	D1	D ¹	E2	E ¹	G2	G ¹
H4	0	D0	D ⁰	D0	D ⁰	E0	E ⁰	G0	G ⁰
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	-	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
J4	0	E0	E ⁰	E0	E ⁰	H0	H ⁰	J0	J ⁰
J3	0	E2	E ¹	E1	E ¹	H2	H ¹	J2	J ¹
J2	0	E4	E ²	E2	E ²	H4	H ²	J4	J ²
J1	0	E6	E ³	E4	E ³	H6	H ³	J6	J ³
K1	0	E8	E ⁴	E6	E ⁴	H8	H ⁴	J8	J ⁴
J5	0	E10	E ⁵	E8	E ⁵	H10	H ⁵	J10	J ⁵
K2	0	E12	E ⁶	E9	E ⁶	H12	H ⁶	J12	J ⁶

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA (Cont.)**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
J6	0	E14	E ⁷	E10	E ⁷	H14	H ⁷	J14	J ⁷
K3	0	NC	-	E12	E ⁸	G0	G ⁰	I0	I ⁰
K4	0	NC	-	E14	E ⁹	G2	G ¹	I4	I ¹
L1	0	NC	-	NC	-	I14	I ⁷	K0	K ⁰
L2	0	NC	-	NC	-	I12	I ⁶	K2	K ¹
M1	0	NC	-	NC	-	NC	-	K4	K ²
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
-	0	-	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
M2	0	NC	-	NC	-	NC	-	K6	K ³
N1	0	NC	-	NC	-	I10	I ⁵	K8	K ⁴
M3	0	NC	-	NC	-	I8	I ⁴	K10	K ⁵
M4	0	NC	-	F0	F ⁰	G4	G ²	I8	I ²
N2	0	NC	-	F1	F ¹	G6	G ³	I12	I ³
K5	0	F0	F ⁰	F2	F ²	J0	J ⁰	N0	N ⁰
P1	0	F2	F ¹	F4	F ³	J2	J ¹	N2	N ¹
K6	0	F4	F ²	F6	F ⁴	J4	J ²	N4	N ²
N3	0	F6	F ³	F8	F ⁵	J6	J ³	N6	N ³
L5	0	F8	F ⁴	F9	F ⁶	J8	J ⁴	N8	N ⁴
P2	0	F10	F ⁵	F10	F ⁷	J10	J ⁵	N10	N ⁵
L6	0	F12	F ⁶	F12	F ⁸	J12	J ⁶	N12	N ⁶
R1	0	F14	F ⁷	F14	F ⁹	J14	J ⁷	N14	N ⁷
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
P3	-	TCK	-	TCK	-	TCK	-	TCK	-
-	-	VCC	-	VCC	-	VCC	-	VCC	-
-	-	GND	-	GND	-	GND	-	GND	-
-	0	-	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
T2	0	NC	-	G14	G ⁹	I6	I ³	K12	K ⁶
M5	0	NC	-	G12	G ⁸	I4	I ²	K14	K ⁷
N4	0	G14	G ⁷	G10	G ⁷	K14	K ⁷	O14	O ⁷
T3	0	G12	G ⁶	G9	G ⁶	K12	K ⁶	O12	O ⁶
R3	0	G10	G ⁵	G8	G ⁵	K10	K ⁵	O10	O ⁵
M6	0	G8	G ⁴	G6	G ⁴	K8	K ⁴	O8	O ⁴
P4	0	G6	G ³	G4	G ³	K6	K ³	O6	O ³
L7	0	G4	G ²	G2	G ²	K4	K ²	O4	O ²
N5	0	G2	G ¹	G1	G ¹	K2	K ¹	O2	O ¹
M7	0	G0	G ⁰	G0	G ⁰	K0	K ⁰	O0	O ⁰
P5	0	NC	-	NC	-	G8	G ⁴	M0	M ⁰
R4	0	NC	-	NC	-	G10	G ⁵	M4	M ¹
T4	0	NC	-	NC	-	NC	-	L0	L ⁰
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA (Cont.)**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
E7	0	NC	-	B1	B ¹	F8	F ⁴	D12	D ³
A3	0	B0	B ⁰	B2	B ²	B0	B ⁰	B0	B ⁰
F7	0	B2	B ¹	B4	B ³	B2	B ¹	B2	B ¹
B4	0	B4	B ²	B6	B ⁴	B4	B ²	B4	B ²
C5	0	B6	B ³	B8	B ⁵	B6	B ³	B6	B ³
A2	0	B8	B ⁴	B9	B ⁶	B8	B ⁴	B8	B ⁴
E6	0	B10	B ⁵	B10	B ⁷	B10	B ⁵	B10	B ⁵
B3	0	B12	B ⁶	B12	B ⁸	B12	B ⁶	B12	B ⁶
C4	0	B14	B ⁷	B14	B ⁹	B14	B ⁷	B14	B ⁷
D4	0	NC	-	NC	-	D10	D ⁵	F0	F ⁰
E5	0	NC	-	NC	-	D8	D ⁴	F2	F ¹
-	-	VCC	-	VCC	-	VCC	-	VCC	-
-	-	-	-	-	-	GND	-	GND	-
-	0	-	-	-	-	GND (Bank 0)	-	GND (Bank 0)	-

Note: VCC, VCCO and GND are tied together to their respective common signal on the package substrate. See Power Supply and NC Connections table for VCC/ VCCO/GND pin definitions.

ispMACH 4000B (2.5V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032B	LC4032B-5T48I	32	2.5	5	TQFP	48	32	I
	LC4032B-75T48I	32	2.5	7.5	TQFP	48	32	I
	LC4032B-10T48I	32	2.5	10	TQFP	48	32	I
	LC4032B-5T44I	32	2.5	5	TQFP	44	30	I
	LC4032B-75T44I	32	2.5	7.5	TQFP	44	30	I
	LC4032B-10T44I	32	2.5	10	TQFP	44	30	I
LC4064B	LC4064B-5T100I	64	2.5	5	TQFP	100	64	I
	LC4064B-75T100I	64	2.5	7.5	TQFP	100	64	I
	LC4064B-10T100I	64	2.5	10	TQFP	100	64	I
	LC4064B-5T48I	64	2.5	5	TQFP	48	32	I
	LC4064B-75T48I	64	2.5	7.5	TQFP	48	32	I
	LC4064B-10T48I	64	2.5	10	TQFP	48	32	I
	LC4064B-5T44I	64	2.5	5	TQFP	44	30	I
	LC4064B-75T44I	64	2.5	7.5	TQFP	44	30	I
	LC4064B-10T44I	64	2.5	10	TQFP	44	30	I
LC4128B	LC4128B-5T128I	128	2.5	5	TQFP	128	92	I
	LC4128B-75T128I	128	2.5	7.5	TQFP	128	92	I
	LC4128B-10T128I	128	2.5	10	TQFP	128	92	I
	LC4128B-5T100I	128	2.5	5	TQFP	100	64	I
	LC4128B-75T100I	128	2.5	7.5	TQFP	100	64	I
	LC4128B-10T100I	128	2.5	10	TQFP	100	64	I
LC4256B	LC4256B-5FT256AI	256	2.5	5	ftBGA	256	128	I
	LC4256B-75FT256AI	256	2.5	7.5	ftBGA	256	128	I
	LC4256B-10FT256AI	256	2.5	10	ftBGA	256	128	I
	LC4256B-5FT256BI	256	2.5	5	ftBGA	256	160	I
	LC4256B-75FT256BI	256	2.5	7.5	ftBGA	256	160	I
	LC4256B-10FT256BI	256	2.5	10	ftBGA	256	160	I
	LC4256B-5F256AI ¹	256	2.5	5	fpBGA	256	128	I
	LC4256B-75F256AI ¹	256	2.5	7.5	fpBGA	256	128	I
	LC4256B-10F256AI ¹	256	2.5	10	fpBGA	256	128	I
	LC4256B-5F256BI ¹	256	2.5	5	fpBGA	256	160	I
	LC4256B-75F256BI ¹	256	2.5	7.5	fpBGA	256	160	I
	LC4256B-10F256BI ¹	256	2.5	10	fpBGA	256	160	I
	LC4256B-5T176I	256	2.5	5	TQFP	176	128	I
	LC4256B-75T176I	256	2.5	7.5	TQFP	176	128	I
	LC4256B-10T176I	256	2.5	10	TQFP	176	128	I
	LC4256B-5T100I	256	2.5	5	TQFP	100	64	I
	LC4256B-75T100I	256	2.5	7.5	TQFP	100	64	I
	LC4256B-10T100I	256	2.5	10	TQFP	100	64	I

ispMACH 4000V (3.3V) Lead-Free Extended Temperature Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-75TN48E	32	3.3	7.5	Lead-free TQFP	48	32	E
	LC4032V-75TN44E	32	3.3	7.5	Lead-free TQFP	44	30	E
LC4064V	LC4064V-75TN100E	64	3.3	7.5	Lead-free TQFP	100	64	E
	LC4064V-75TN48E	64	3.3	7.5	Lead-free TQFP	48	32	E
	LC4064V-75TN44E	64	3.3	7.5	Lead-free TQFP	44	30	E
LC4128V	LC4128V-75TN144E	128	3.3	7.5	Lead-free TQFP	144	96	E
	LC4128V-75TN128E	128	3.3	7.5	Lead-free TQFP	128	92	E
	LC4128V-75TN100E	128	3.3	7.5	Lead-free TQFP	100	64	E
LC4256V	LC4256V-75TN176E	256	3.3	7.5	Lead-free TQFP	176	128	E
	LC4256V-75TN144E	256	3.3	7.5	Lead-free TQFP	144	96	E
	LC4256V-75TN100E	256	3.3	7.5	Lead-free TQFP	100	64	E

For Further Information

In addition to this data sheet, the following technical notes may be helpful when designing with the ispMACH 4000V/B/C/Z family:

- TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#)
- TN1005, [Power Estimation in ispMACH 4000V/B/C/Z Devices](#)

Revision History

Date	Version	Change Summary
—	—	Previous Lattice releases.
July 2003	17z	Changed device status for LC4064ZC and LC4128ZC to production release and updated/added AC and DC parameters as well as ordering part numbers for LC4064ZC and LC4128ZC devices.
		Improved leakage current specifications for ispMACH 4000Z. For ispMACH 4000V/B/C IIL, IIH condition now includes 0V and 3.6V end points ($0 \leq V_{IN} \leq 3.6V$).
		Added 132-ball chip scale BGA power supply and NC connections.
		Added 132-ball chip scale BGA logic signal connections for LC4064ZC, LC4128ZC and LC4256ZC devices.
		Added lead-free package designators.
October 2003	18z	Hot socketing characteristics footnote 1. has been enhanced; Insensitive to sequence of VCC or VCCO. However, assumes monotonic rise/fall rates for Vcc and Vcco, provided $(V_{IN} - V_{CCO}) \leq 3.6V$.
		Improved LC4064ZC t _S to 2.5ns, t _{ST} to 2.7ns and f _{MAX} (Ext.) to 175MHz, LC4128ZC t _{CO} to 3.5ns and f _{MAX} (Ext.) to 161MHz (version v.2.1).
		Improved associated internal timing numbers and timing adders (version v.2.1).
		Added ispMACH 4000V/B/C/Z ORP Reference Tables.
		Enhanced ORP information in device pinout tables consistent with the ORP Combinations for I/O Blocks tables (table 6, 7, 8 and 9 in page 9-11).
		Corrected GLB/MC/Pad information in the 256-fpBGA pinouts for the LC4256V/B/C 160-I/O version.
		Added the ispMACH 4000 Family Speed Grade Offering table.
		Added the ispMACH 4128ZC Industrial and Automotive Device OPNs
December 2003	19z	Added the ispMACH 4032ZC and 4064ZC Industrial and Automotive Device OPNs